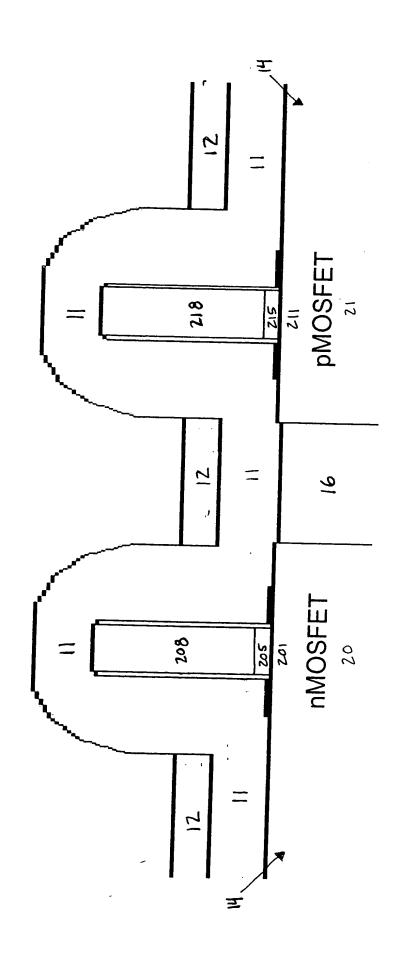
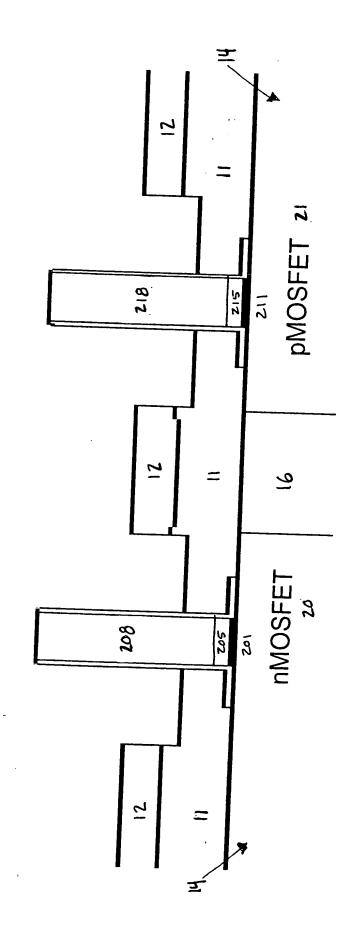


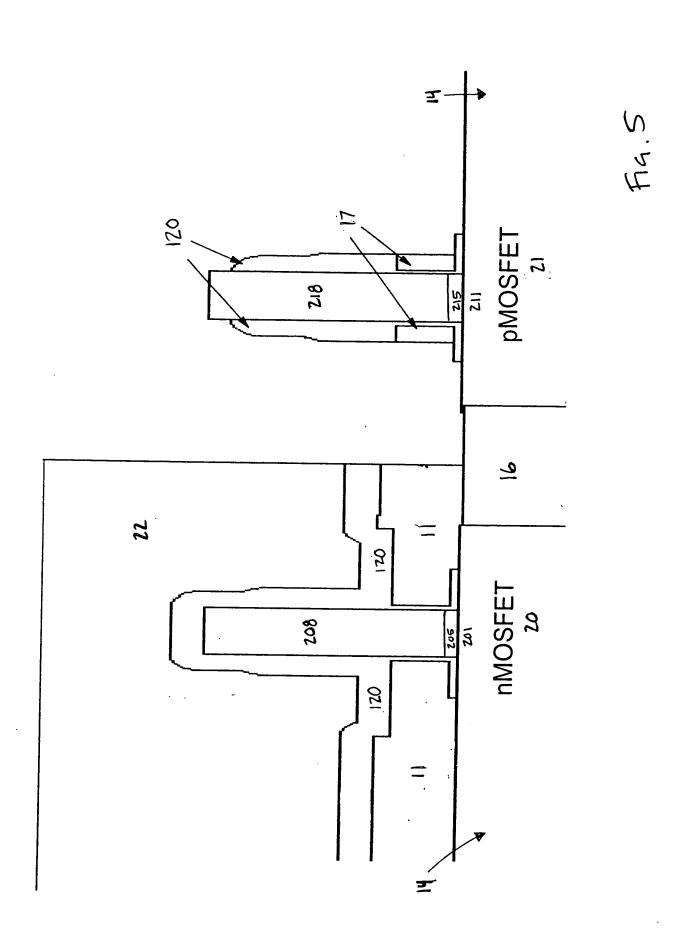
F14.2

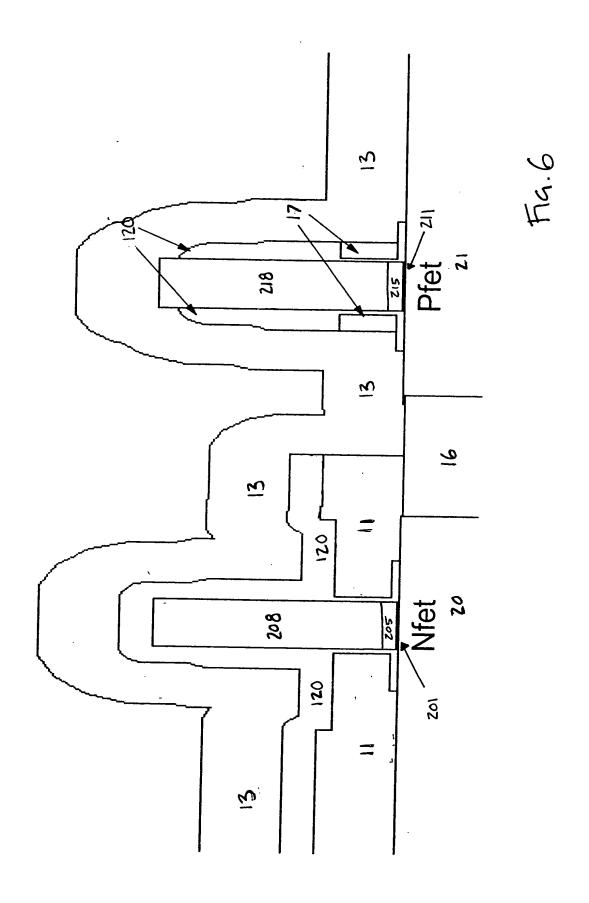


F19.3



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Numerical simulation for claimed structure:

Stress along x-axis/lateral direction, Sxx, cut at 5 nm below gate-oxide

(Thickness of the compressive and tensile nitride films is 50 nm.

In nMOSFET channel Sxx= + 190MPa and Sxx= - 300MPa in pMOSFET channel.

The intrinsic stress in the tensile and compressive nitride films, Sxx_intrisic = +/- 1.8GPa)

1.00 F19.7 **pMOSFET** channel 8. 8 Stress, Sxx, (dynesノcm゚2) 09.0 trench 0.40 ଷ . ଷ **nMOSFET** channel

> ģ XXS

-5,00+09

60+60.1

5°09+08

0 0 0

60+60'+-

